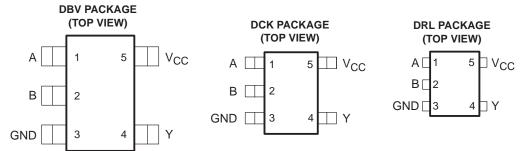
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- Operating Range of 4.5 V to 5.5 V
- Max t<sub>pd</sub> of 8 ns at 5 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

#### description/ordering information

The SN74AHCT1G32 is a single 2-input positive-OR gate. The device performs the Boolean function Y = A + B or  $Y = \overline{A} \bullet \overline{B}$  in positive logic.

#### ORDERING INFORMATION

TA	PACKAGE	<u></u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
-40°C to 85°C	COT (COT 02) DDV	Reel of 3000	SN74AHCT1G32DBVR	Dag	
	SOT (SOT-23) – DBV	Reel of 250	SN74AHCT1G32DBVT	B32_	
	COT (CC 70) DOK	Reel of 3000	SN74AHCT1G32DCKR	DC.	
	SOT (SC-70) – DCK	Reel of 250	SN74AHCT1G32DCKT	BG_	
	SOT (SOT-553) - DRL	Reel of 4000	SN74AHCT1G32DRLR	BG_	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

ı	INP	JTS	OUTPUT
ı	Α	В	Υ
ı	Н	Χ	Н
ı	X	Н	Н
	L	L	L

#### logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> The actual top-side marking has one additional character that designates the assembly/test site.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Note 1)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{ K }(V_{ C } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DBV package	206°C/W
DCK package	252°C/W
DRL package	142°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		8.0	V
VI	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS	Vaa	T	չ = 25°C	;	MAINI	MAX	LINUT
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	MIN	WIIN WAX	UNIT
\/a	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		\/
Voн	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V
V	$I_{OL} = 50 \mu A$	451/			0.1		0.1	٧
VOL	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44	
lį	$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10	μΑ
∆l <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2	10		10	pF

 $<sup>\</sup>ddagger$  This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

### SN74AHCT1G32 SINGLE 2-INPUT POSITIVE-OR GATE

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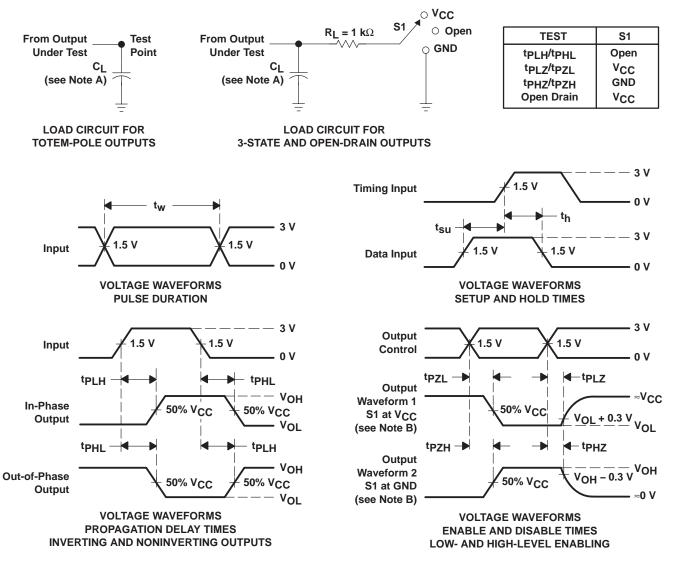
# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	չ = 25°C	;		BA A V	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A = = D	V	0. 45 = 5		5	6.9	1	8	
t <sub>PHL</sub>	A or B	Y	C <sub>L</sub> = 15 pF		5	6.9	1	8	ns
<sup>t</sup> PLH	A or B	V	C: _ 50 pE		5.5	7.9	1	9	ne
t <sub>PHL</sub>	AUID	ſ	C <sub>L</sub> = 50 pF		5.5	7.9	1	9	ns

## operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	11.5	pF

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>I</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM





#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AHCT1G32DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G32DRLRG4	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G32DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G32DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G32DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G32DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G32DRLR	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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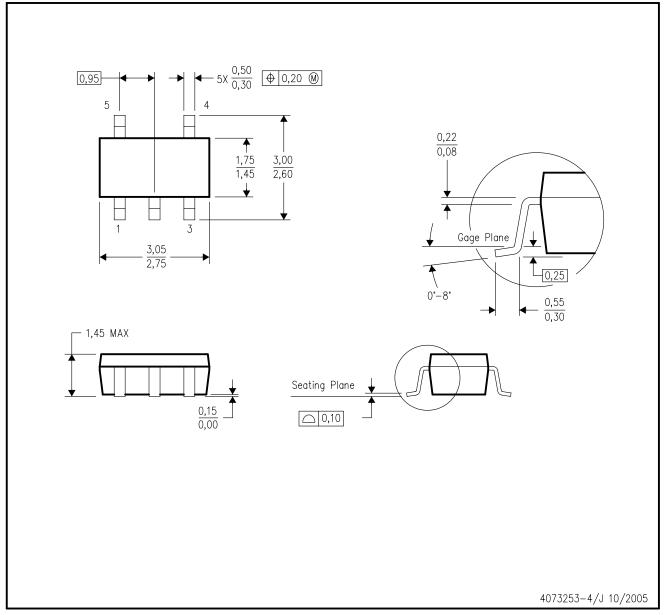
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# DBV (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE



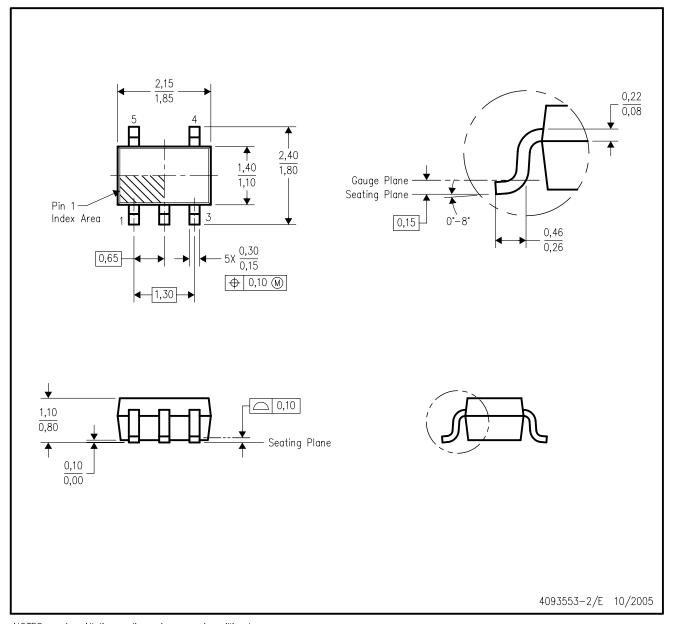
NOTES:

- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.



# DCK (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE



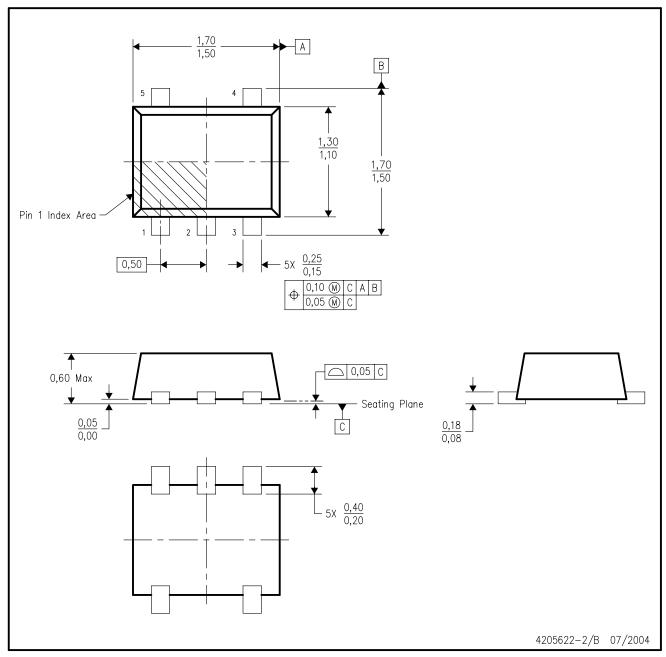
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



# DRL (R-PDSO-N5)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. JEDEC package registration is pending.



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